



Miniature RF switch for compact redundancy ring

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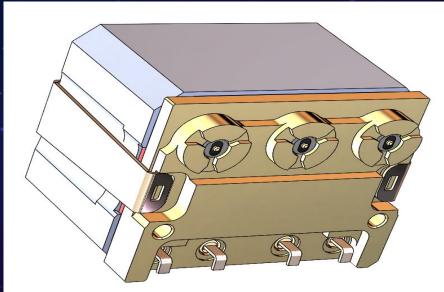
This project has received funding from European Union's Horizon 2020 research and innovation programme under grant agreement N° 821973

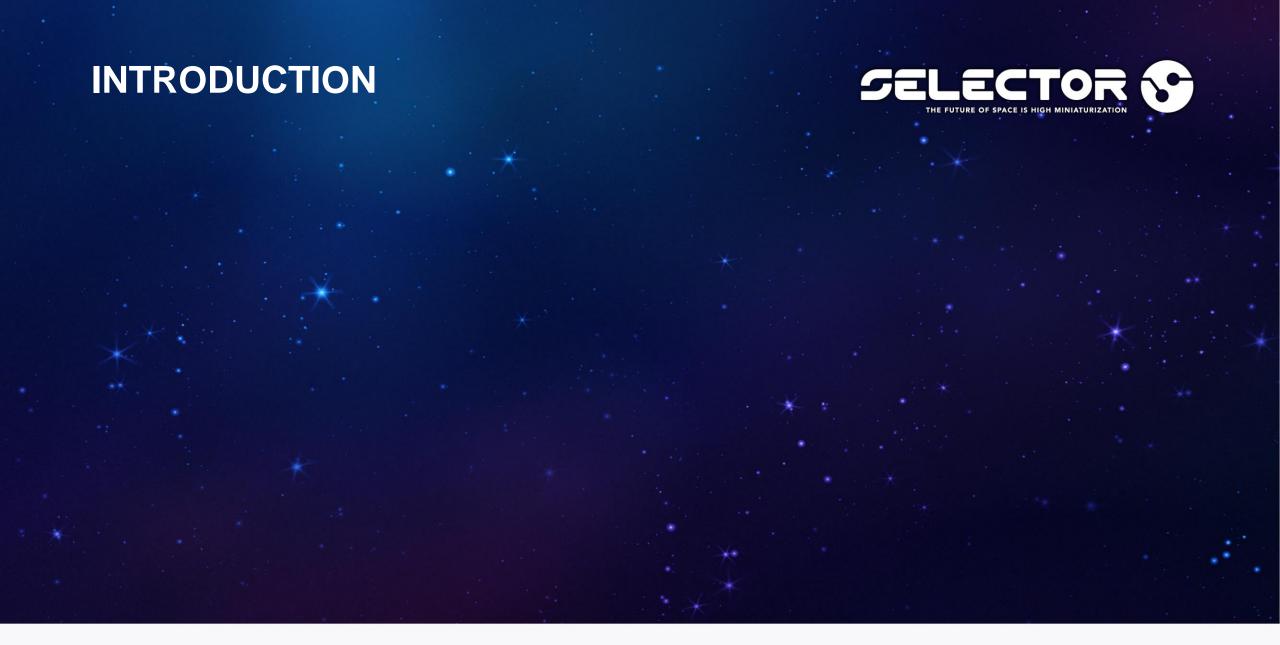


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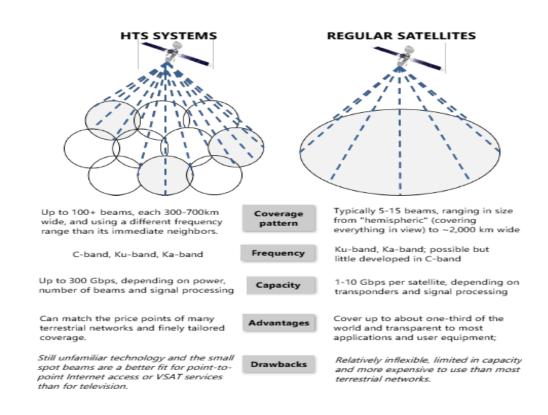




NEW TELECOM PAYLOAD TECHNOLOGY TRENDS



- Satellite telecom market is changing from the classical television broadcast application towards an IP-based broadband market requiring Very High Throughput Satellites (high capacity x100 Gbps) and flexibility to mitigate business uncertainties
- New Telecom payloads based on highly capacitive digital processors and active antennas are currently proposed, leading to important changes for microwave units in terms of architecture and technologies to cope with cost, mass, integration, DC consumption, thermal dissipation and redundancy/connectivity challenges.

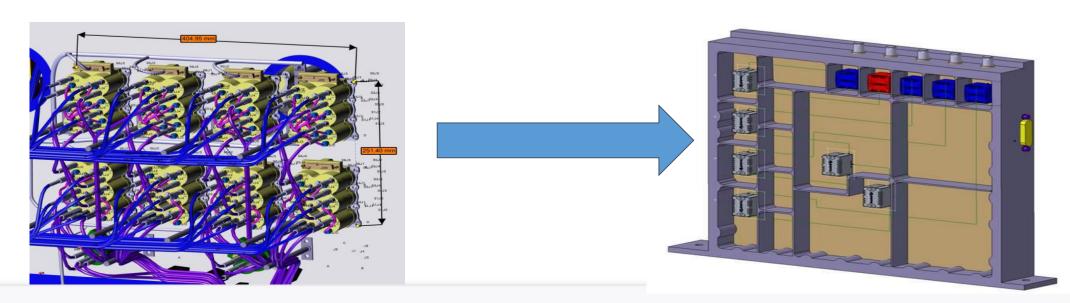




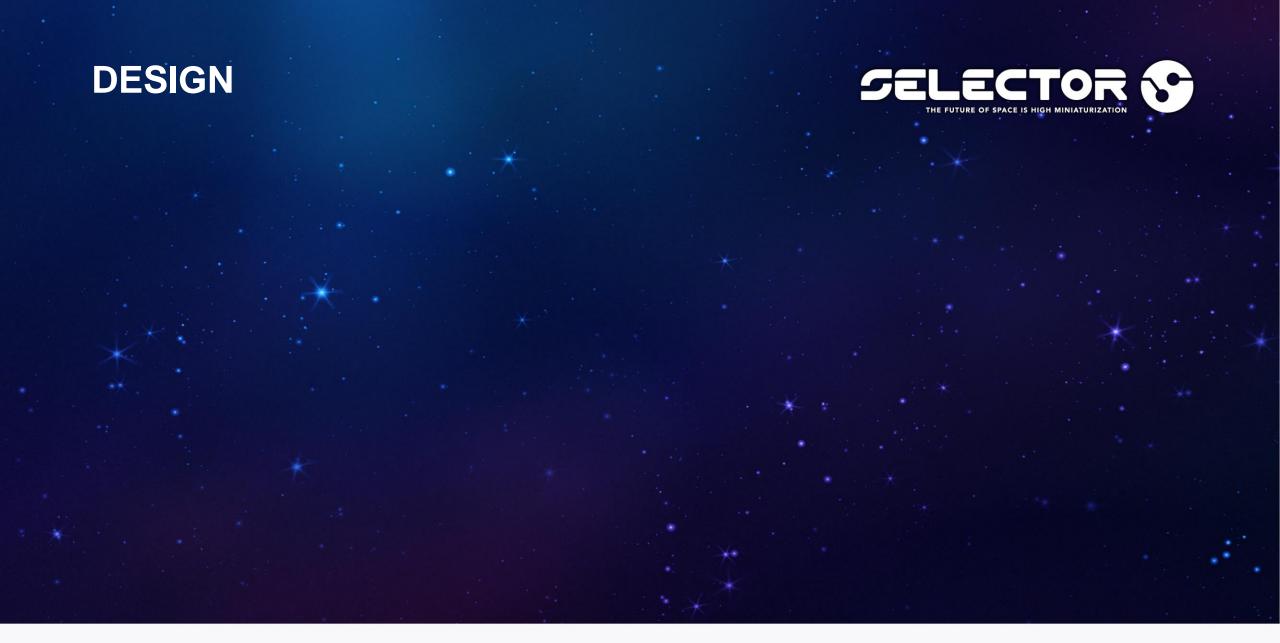
TARGET



- Use of a new component: Micro Electro Mechanical Relay (MEMR) SMT compatible
- Enable highly demanding connectivity within reconfigurable new generation processed telecompayload
- Compatibility with RF on PCB technology, keeping mass and volume at minimum as compared to standard RF harness complex connectivity matrices









DESIGN



- Development based on Quartz series: this relay has already been qualified for test & measurements and MIL market → significant heritage and return on experience
- How to meet space requirements?
 - Waterproof (IP 67)
 - Microwave performance (DC- 32 GHz)
 - Improve shielding effectiveness (< 40dB)
 - Gain in mass compared to existing Quartz (standard) version
 - Harsh environment (random vibrations 50Grms 10 to 2000 Hz, mechanical shocks up to 3000g)



WATERPROOF



• Why ?

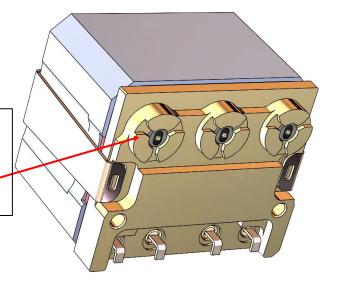
 To facilitate the cleaning of the soldering area.

Where ?

 The unique weakness of this switch about hermeticity against liquid was the RF access.

• How ?

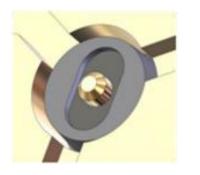
 In order to be IP67 we had to adapt the structure of the switch by adding a resin on the insulator RF port: coaxial line usually with non hermetic insulator



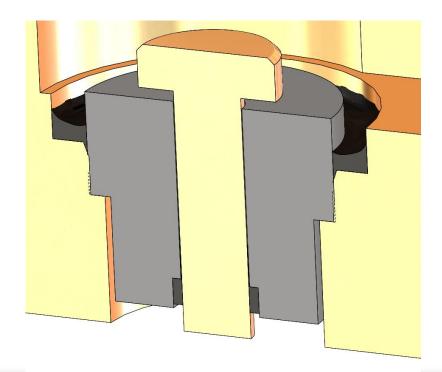


WATERPROOF

- Optimized glue shape
- Ridge to prevent glue bleeding
- Optimized glue thickness
- Counterbore to facilitate the glue deposit





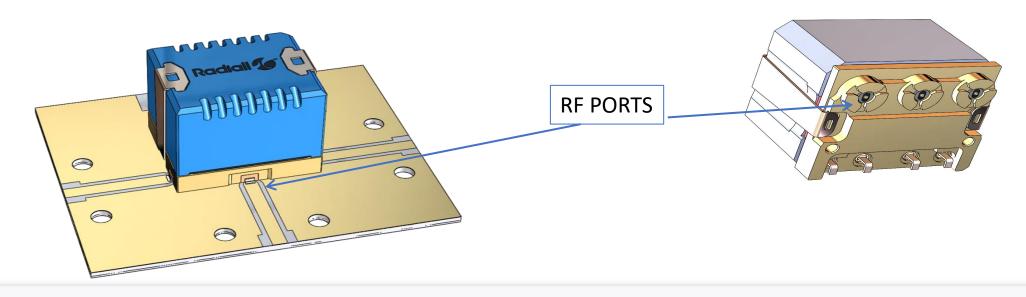




RF PERFORMANCES IMPROVEMENTS



- RF ports have been modified to meet new requirements:
 - Hermeticity
 - Direction of RF ports
 - => The whole RF line has been redesigned and optimized

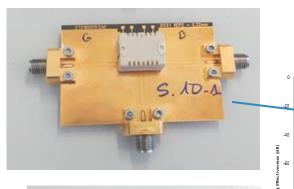


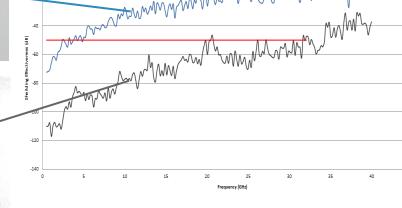


RF PERFORMANCES IMPROVEMENTS



- Some improvements were performed to increase RF shielding effectiveness such as
 - Metallic cap,
 - Conductive gasket,
 - Shielding of RF access,
 - Shielding of Printed Circuit Board
- These improvements allow to reach
 -50dB typical of shielding effectiveness



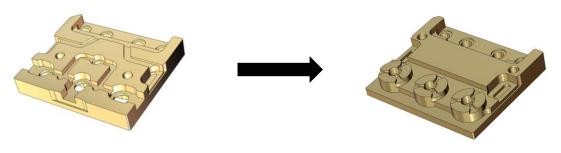


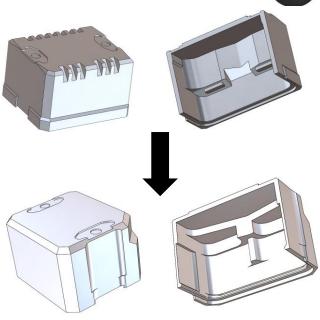


GAIN IN MASS

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- The cover
 - Use of aluminium to improve shielding effectiveness increases the weight
 - Shape optimization, remove material:
 - $2.05 g \Rightarrow 1.23 g$.
- The RF plate
 - Shape optimization of the RF body:
 - Same process as the cover, less material:
 - $2.65 g \Rightarrow 2.33 g$.



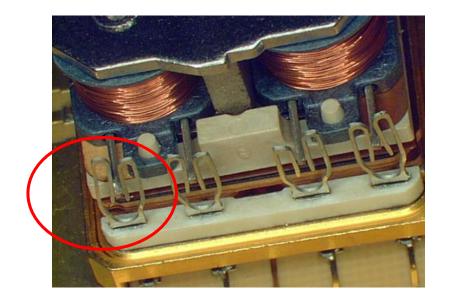




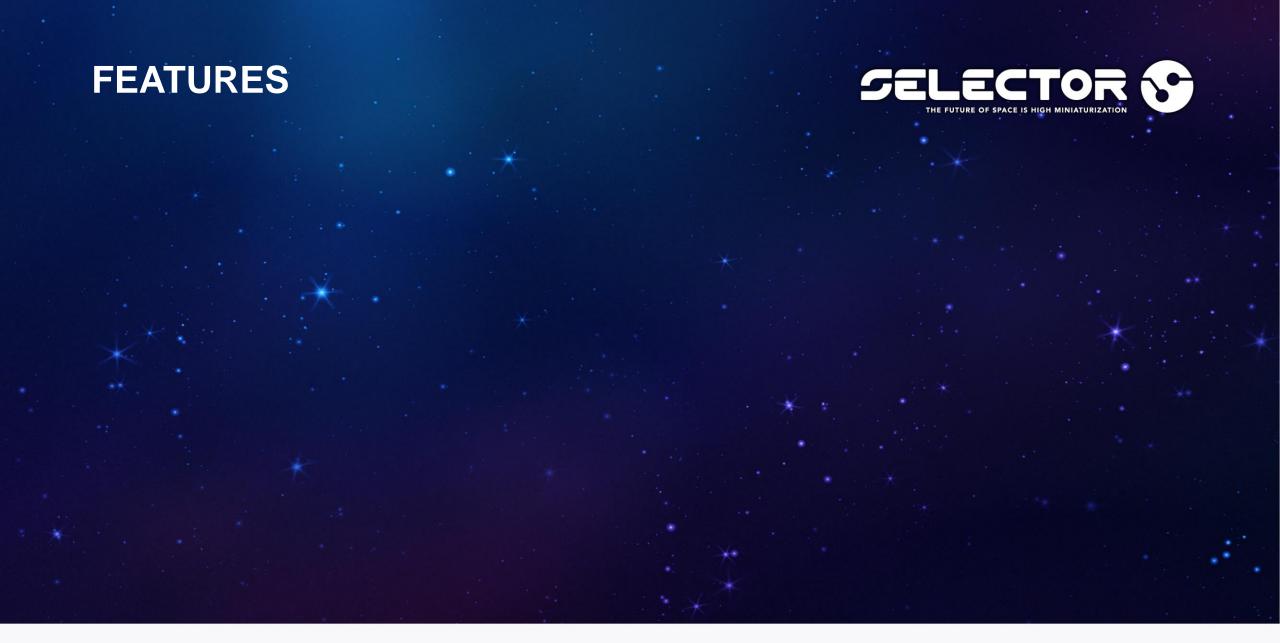
HARSH ENVIRONMENT

SELECTOR S

- Harsh environment (Vibrations and shocks):
 - Pins induce resonance and deform the coil contacts
 - To resist such vibration levels, the coils have to be immobilized.









DESCRIPTION OF THE RELAY



SPDT : Single Port Double Throws

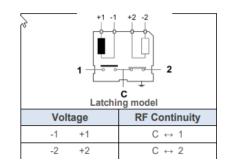
Latching, without telemetry

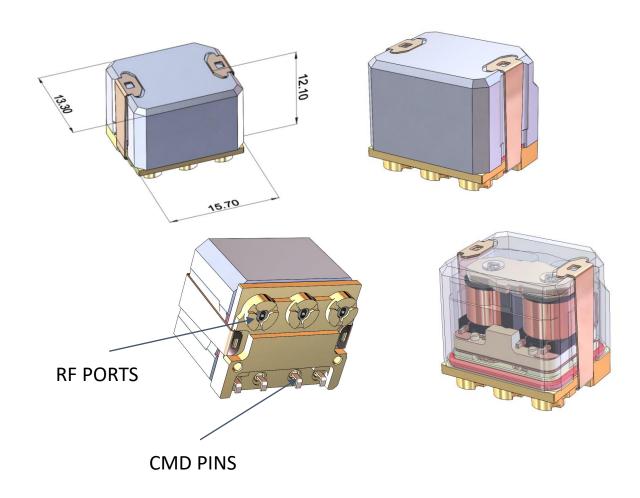
Actuation voltage : 6 or 12 V

• Frequency band: DC - 32 GHz

• Weight: 7.5 g

Dimensions: 15.7 x 13.3 x 12.1 mm

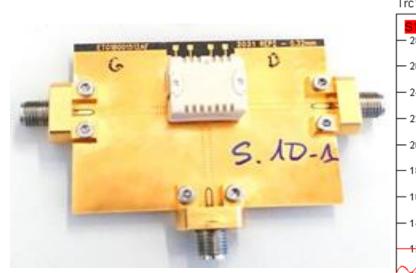


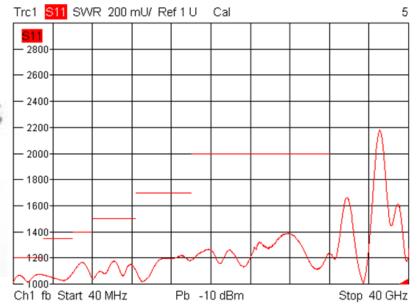


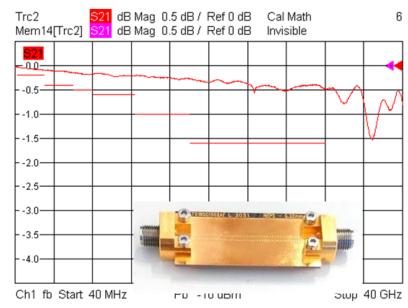




Microwave performance improvement - StackUp HF Measurement





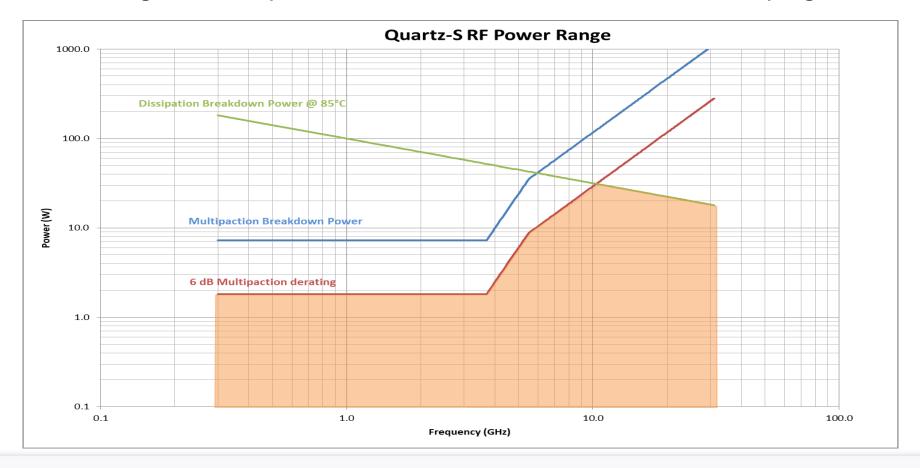


Circuit Losses subtracted





• Power Handling and Multipaction: based on simulation and test campaigns







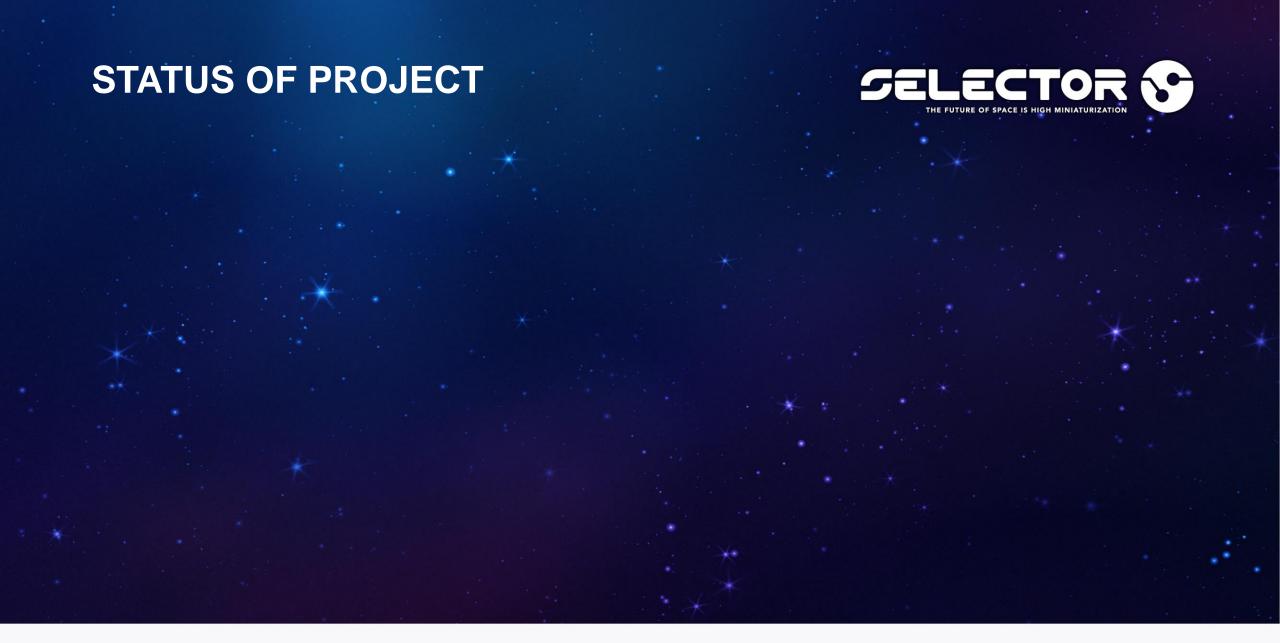
Characteristics	SPDT QUARTZ-S
Size (L x l x h)	15.4 x 13.3 x 12.1 mm
Mass	Less than 10 g
Interface	SMT (coaxial line, gold plated access)
Sealing	Waterproof IP67
Vibration	Random 50 Grms overall Sine 30g
Mechanical shocks	1500 g / 0.3ms, ½ sine
Temperature range	-40 °C / + 85°C
Operating mode	Latching





Characteristics	SPDT QUARTZ-S					
Frequency	DC - 32 GHz					
VSWR max	<1.25					
IL (dB typical)	Typical : < 0.2 @ 3 GHz; < 0.6 @ 32 GHz					
Isolation (dB min)	45					
EMI Shielding (dBi min)	- 40					
Supply voltage (Volts)	6 or 12					
Switching time (ms max)	5					
Actuation life	1 million cycles (cold switching) 500 000 cycles (Hot switching, 1W)					







QUALIFICATION

SELECTOR S

• Specifications: generic & detail

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RELAYS, ELECTROMAGNETIC, RF SWITCH, LATCHING

ESCC Generic Specification No. 3603



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RF ELECTROMAGNETIC RELAY, LATCHING, SMT, Micro-SPDT, BREAK-BEFORE-MAKE, LOW POWER, DC TO 32GHz

ESCC Detail Specification No. 323 (3603/007)



QUALIFICATION TEST PLAN



L	LATCHING	SELECTO	OR SMT P	ower Micro	-SPDT 32	GHz		
Ref		R517831611						
SN	1	2	3	4	5	6	1	2
Degolding on RF pins	•	•					•	•
Solder heat Test	•	•	•	•	•	•	•	•
Soldering on PCB	•	•	•	•	•	•	•	•
Cleaning	•	•	•	•	•	•	•	•
Visual Inspection test (1)	•	•	•	•	•	•	•	•
Initial functional test	•	•	•	•	•	•	•	•
Visual inspection test (2)	•	•	•	•	•	•	•	•
Sine survey test (1)	•	•	•	•	•	•	•	•
Sine vibration test	•	•	•	•	•	•	•	•
Sine survey test (2)	•	•	•	•	•	•	•	•
Random vibration test	•	•	•	•	•	•	•	•
Sine survey test (3)	•	•	•	•	•	•	•	•
Visual inspection test (3)	•	•	•	•	•	•	•	•
Mechanical shock test	•	•	•	•	•	•	•	•
Sine survey test (4)	•	•	•	•	•	•	•	•
Thermal Vacuum	•	•	•	•	•	•	•*	•
Life test (cold switching)	•		•	•				
Life test (hot switching)		•			•	•		•
EMC	•	•	•	•	•	•		•
Final functional test	•	•	•	•	•	•		•
Seat test	•	•	•	•	•	•		•
DPA	•	•	•	•	•	•	•	

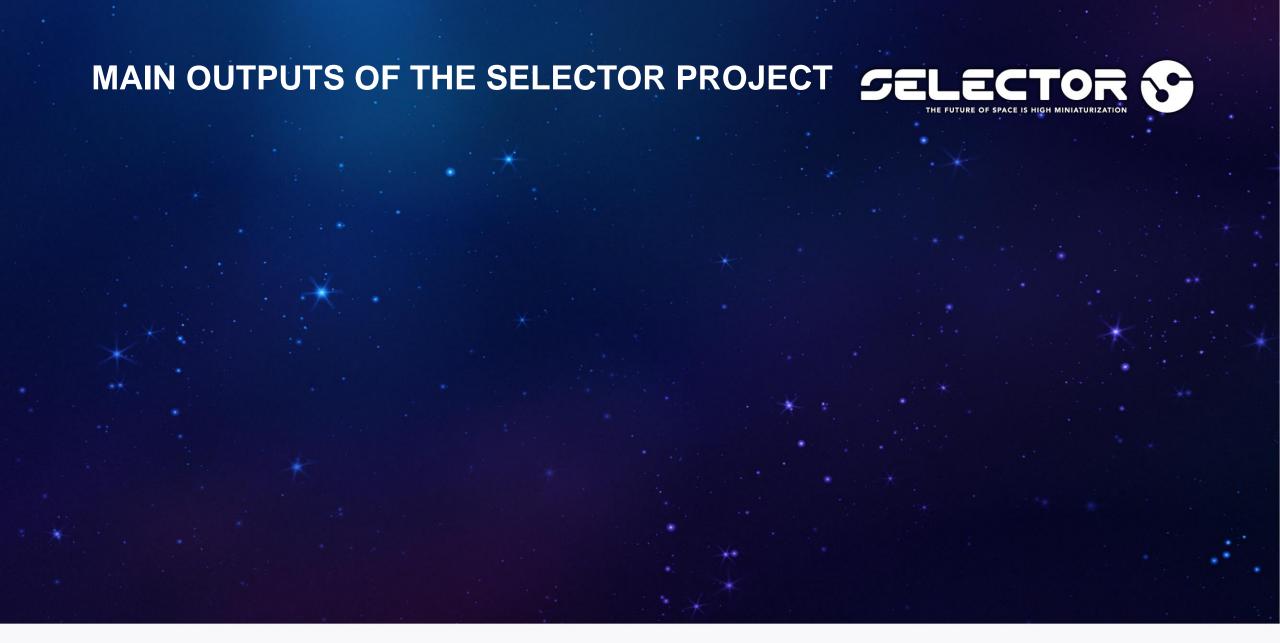


STATUS OF QUALIFICATION



- ✓ Qualification test according to ESCC3603 => EPPL in 2022
- ✓ Industrialization: done
- ✓ Few hundreds of EM already delivered
- First FM batch (200p) to be delivered in november 2022
- Target: to be ESA QPL in 2023





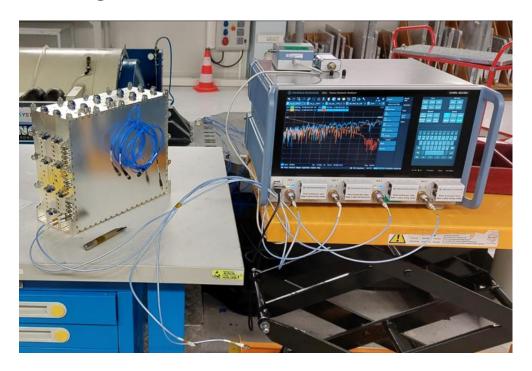


MAJOR ACHIEVEMENTS

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- MEMR SPDT switch component validating a TRI 6
- Dedicated redundancy ring building blocks validated up to a TRL 6
 - I/O interconnects
 - SMT mounting of MEMR
 - Multilayer RF PCB
- MEMR SPDT demonstration into a compact redundancy ring using RF on PCB technologies available at TAS validating a TRL 3
 - Up to 2 redundancy rings 27:30 into the same assembly
 - Scalable patented architecture and design
 - Wide band frequency

Assembly of 3 slices prior to vibration testing



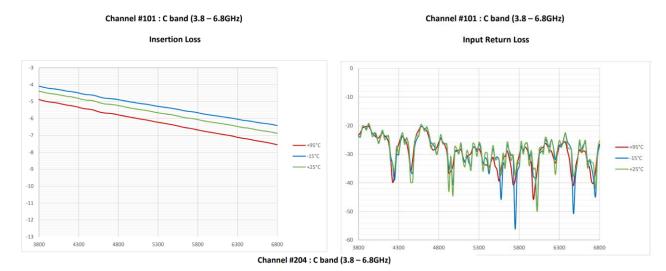


MAJOR ACHIEVEMENTS



- Performance assessment in C band
 - Return loss better than -20 dB
 - Less than 3 dB insertion loss between shortest/longest path
 - Channel to channel RF isolation better than -65 dB
 - Temperature range validation : from -15 to 95 °C
- Good match between measurements and 3D EM RF multiscale models
- Next: Further effort for equipment industrialization and higher frequency operation

S parameter measurement vs temperature



Isolation J18 -> J19

